

C0805X160MATACTU

Aliases (C0805X160MATAC7800) SMD Comm X8G HT150C Flex, Ceramic, 16 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0805, 0.6 mm



Click here for the 3D model.

| General Information | | |
|--------------------------|--|--|
| Series | SMD Comm X8G HT150C Flex | |
| Style | SMD Chip | |
| Description | SMD, MLCC, High Temperature, Ultra-Stable | |
| Features | High Temperature, Ultra-Stable | |
| RoHS | Yes | |
| Termination | Flexible Termination | |
| Marking | No | |
| AEC-Q200 | No | |
| Typical Component Weight | 11 mg | |
| Shelf Life | 78 Weeks | |
| MSL | 1 | |

Time is 1000 Hours

100 GOhms

| | Specifications | |
|--------------------------|--|------------------------------|
| 0805 | Capacitance | 16 pF |
| 2mm +/-0.3mm | Measurement Condition | 1 MHz 1.0Vrms |
| 1.25mm +/-0.3mm | Tolerance | 20% |
| 0.78mm +/-0.20mm | Voltage DC | 250 VDC |
| 0.6mm MIN | Dielectric Withstanding Voltage | 625 VDC |
| 0.5mm +/-0.25mm | Temperature Range | -55/+150°C |
| | Temp. Coefficient | X8G |
| T&R, 180mm, Plastic Tape | Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| 4000 | Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| | Aging Rate | 0% Loss/Decade Hour: Referee |

Insulation Resistance

Dimensions

Packaging Specifications

Packaging Quantity

Chip Size

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Packaging